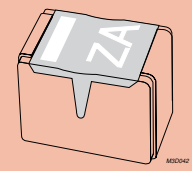
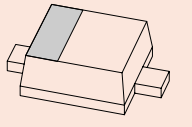
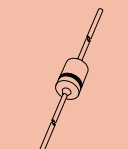
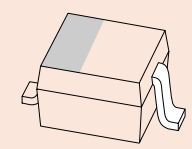
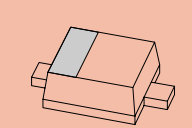
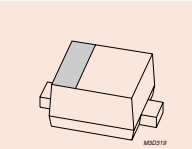
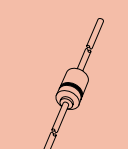
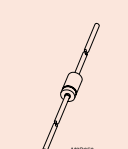
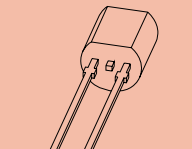


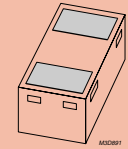
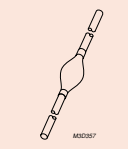
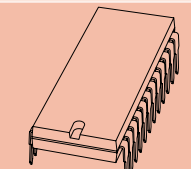
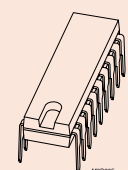
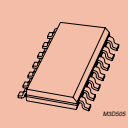
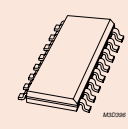
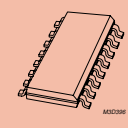



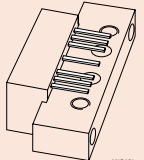
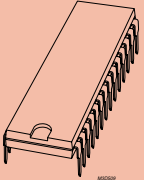
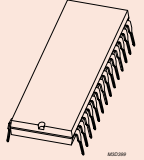
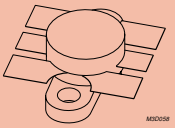
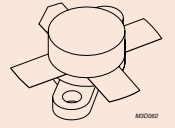
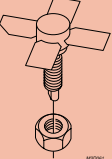
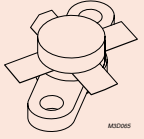
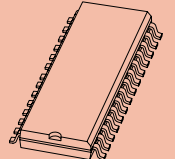
Packages

Package version	Package name	Package description	Industry types	3D Line drawing
SOD110		Very small ceramic rectangular surface mounted package; body 2.0 x 1.25 x 1.6 mm		
SOD123F		Plastic surface mounted package; 2 flatleads; body 2.6 x 1.6 x 1.1 mm		
SOD27	DO-35; SC-40	Hermetically sealed glass package; axial leaded; 2 leads; body 0.65 x 1.85 x 4.25 mm		
SOD323	UMD2; I-IEIA; URP	Plastic surface mounted package; 2 leads; body 1.7 x 1.25 x 0.95 mm	SC-76 (EIAJ)	
SOD323F	SC-90	Plastic surface mounted package; 2 flatleads; body 1.7 x 1.25 x 0.7 mm	SC-90 (JEITA)	
SOD523	I-IGIA; UFP	Plastic surface mounted package; 2 flatleads; body 1.2 x 0.8 x 0.6 mm	SC-79 (EIAJ)	
SOD66	DO-41	Hermetically sealed glass package; axial leaded; 2 leads; body 0.81 x 2.6 x 4.8 mm		
SOD68	DO-34	Hermetically sealed glass package; axial leaded; 2 leads; body 0.55 x 1.6 x 3.04 mm	DO-34 (JEDEC)	
SOD70		Plastic near cylindrical single-ended package; 2 in-line leads; body 5.1 x 4.6 x 3.9 mm		

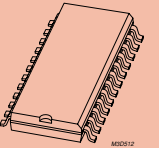
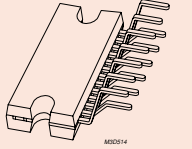
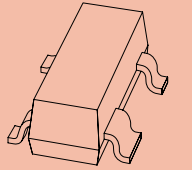
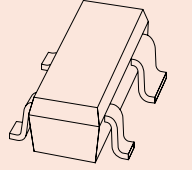
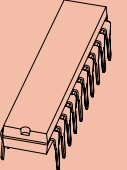
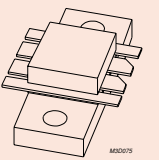
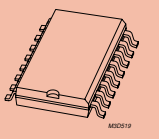
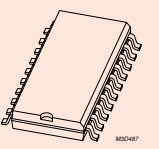
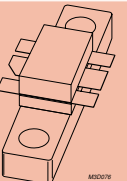
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Package version	Package name	Package description	Industry types	3D Line drawing
SOD80C	LLDS	Hermetically sealed glass surface mounted package; 2 connectors; body 1.53 x 3.5 x 0.3 mm	100H01 (IEC)	
SOD87	LLDL	Hermetically sealed glass surface mounted package; Implotec™ technology; 2 connectors; Implotec is a trademark of Philips; body 2.05 x 1.9 x 3.5 mm	100H01 (IEC)	
SOD882		Leadless ultra small plastic package; 2 terminals; body 1.0 x 0.6 x 0.5 mm		
SOD89B		Hermetically sealed glass package; axial leaded; 2 leads		
SOT101-1	DIP24	plastic dual in-line package; 24 leads (600 mil)	SC-509-24 (EIAJ) MO-015 (JEDEC) 051G02 (IEC)	
SOT102-2	DIP18	plastic dual in-line package; 18 leads (300 mil); slim corner leads	MS-011 (JEDEC)	
SOT108-1	SO14	plastic small outline package; 14 leads; body width 3.9 mm	MS-012 (JEDEC) 076E06 (IEC)	
SOT109	SO16	Plastic small outline package; 16 leads; body width 3.9 mm		
SOT109-1	SO16	plastic small outline package; 16 leads; body width 3.9 mm	MS-012 (JEDEC) 076E07 (IEC)	

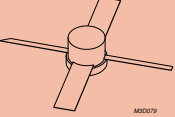
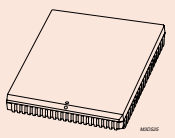
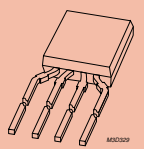
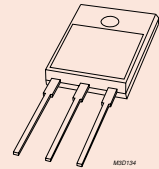
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT109-2	SO16	plastic small outline package; 16 leads; body width 3.9 mm; low stand-off height	MS-012 (JEDEC) 076E07 (IEC)	
SOT115J		Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 7 gold-plated in-line leads		
SOT117-1	DIP28	plastic dual in-line package; 28 leads (600 mil)	SC-510-28 (IEAJ) MO-015 (JEDEC) 051G05 (IEC)	
SOT117-2	DIP28	plastic dual in-line package; 28 leads (600 mil); long body	SC-510-28 (IEAJ) MS-011 (JEDEC) 051G06 (IEC)	
SOT119A		Flanged ceramic package; 2 mounting holes; 6 leads		
SOT121B		Flanged ceramic package; 2 mounting holes; 4 leads		
SOT122A		Studded ceramic package; 4 leads		
SOT123A		Flanged ceramic package; 2 mounting holes; 4 leads		
SOT136-1	SO28	plastic small outline package; 28 leads; body width 7.5 mm	MS-013 (JEDEC) 075E06 (IEC)	

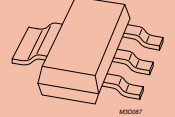
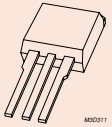
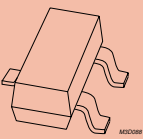
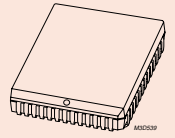
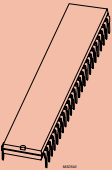
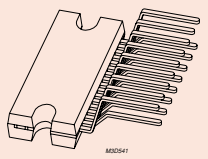
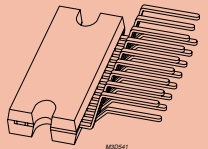
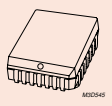
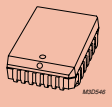
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT137	SO24	plastic small outline package; 24 leads; body 15.4 x 7.5 x 2.35 mm	MS-013 (JEDEC) 075E05 (IEC)	
SOT141	DBS13	Plastic DIL-bent-SIL power package; 13 leads (lead length 7.7 mm)		
SOT143B		Plastic surface mounted package; 4 leads; body 2.9 x 1.3 x 1.0 mm		
SOT143R	SC-61B	Plastic surface mounted package; reverse pinning; 4 leads	SC-61B (EIAJ)	
SOT146-1	DIP20	plastic dual in-line package; 20 leads (300 mil)	SC-603 (EIAJ) MS-001 (JEDEC)	
SOT161A		Flanged ceramic package; 2 mounting holes; 8 leads		
SOT162-1	SO16	plastic small outline package; 16 leads; body 10.3 x 7.5 x 2.35 mm	MS-013 (JEDEC) 075E03 (IEC)	
SOT163-1	SO20	plastic small outline package; 20 leads; body 12.8 x 7.5 x 2.35 mm	MS-013 (JEDEC) 075E04 (IEC)	
SOT171A		Flanged ceramic package; 2 mounting holes; 6 leads		

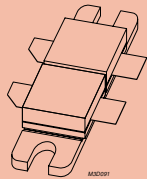
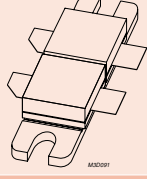
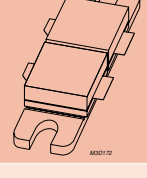
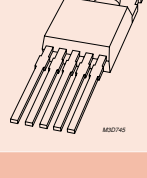
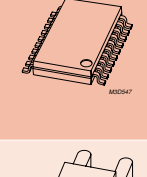
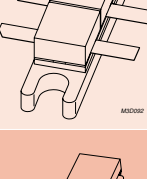
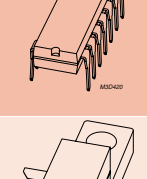
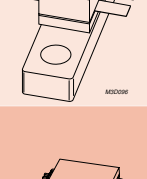
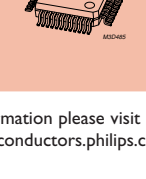
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT172D		Studless ceramic package; 4 leads		
SOT176-1	SO8	plastic small outline package; 8 leads; body 7.55 x 7.5 x 2.35 mm		
SOT186A	3 lead TO-220F	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 lead TO-220 'full pack'	3-lead TO-220F (JEDEC)	
SOT186	TO-220F; SC-67	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 lead TO-220 'full pack' exposed tabs	SC-67 (EIAJ) 3 lead TO-220F (JEDEC)	
SOT187-2	PLCC44	plastic leaded chip carrier; 44 leads; body 16.58 x 16.58 x 4.38 mm	EDR-7319 (EIAJ) MO-047 (JEDEC) 112E10 (IEC)	
SOT189-3	PLCC84	plastic leaded chip carrier; 84 leads; pedestal	MO-047 (JEDEC) 112E13 (IEC)	
SOT195		Plastic single-ended flat package; 4 in-line leads		
SOT199	3-lead TO-247F	Plastic single-ended package; heatsink mounted; 1 mounting hole; 3 lead TO-247 'full pack'	3-lead TO-247F (JEDEC)	
SOT222-1	DIP24	plastic dual in-line package; 24 leads (300 mil)	MS-001 (JEDEC)	

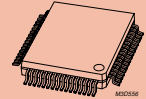
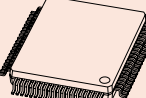
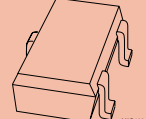
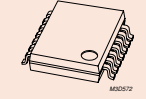
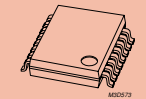
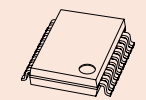
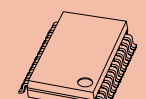
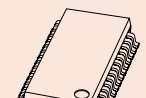
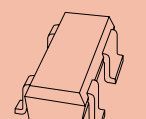
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT223	SC-73	Plastic surface mounted package; collector pad for good heat transfer; 4 leads; body 6.5 x 3.5 x 1.65 mm	SC-73 (EIAJ)	
SOT226	TO-220	Plastic single-ended package; low-profile 3 lead TO-220AB	low-profile 3-lead TO-220AB (JEDEC)	
SOT23	SST3	Plastic surface mounted package; 3 leads; body 2.9 x 1.3 x 1.0 mm	TO-236AB (JEDEC)	
SOT238-3	PLCC52	plastic leaded chip carrier; 52 leads; pedestal	MO-047 (JEDEC) 112E11 (IEC)	
SOT240-1	DIP48	plastic dual in-line package; 48 leads (600 mil)	MS-011 (JEDEC)	
SOT243-1	SIL17; DBS17P	Plastic DIL-bent-SIL power package; 17 leads (lead length 12 mm) Dimensions H x W = 12.2 x 20.0 mm		
SOT261-2	PLCC28	plastic leaded chip carrier; 28 leads		
SOT261-2	PLCC28	plastic leaded chip carrier; 28 leads	EDR-7319 (EIAJ) MS-018 (JEDEC) 112E08 (IEC)	
SOT261-3	PLCC28	plastic leaded chip carrier; 28 leads; pedestal	MO-047 (JEDEC) 112E08 (IEC)	

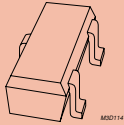
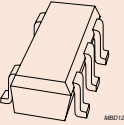
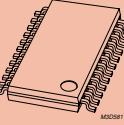
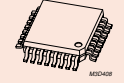
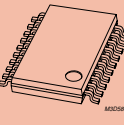
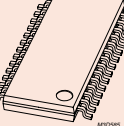
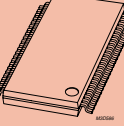
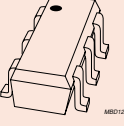
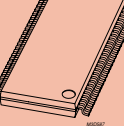
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT262A1		Flanged double-ended ceramic package; 2 mounting holes; 4 leads		
SOT262A2		Flanged double-ended ceramic package; 2 mounting holes; 4 leads		
SOT262B		Flanged double-ended ceramic package; 2 mounting holes; 4 leads		
SOT263B	5-lead TO-220	Plastic single-ended package; heatsink mounted; 1 mounting hole; 5-lead TO-220	5-lead TO-220 (JEDEC)	
SOT266-1	SSOP20	plastic shrink small outline package; 20 leads; body width 4.4 mm	MO-152 (JEDEC)	
SOT268A		Flanged double-ended ceramic package; 2 mounting holes; 4 leads		
SOT27-1	DIP14	plastic dual in-line package; 14 leads (300 mil)	SC-501-14 (EIA) MO-001 (JEDEC) 050G04 (IEC)	
SOT279A		Flanged double-ended ceramic package; 2 mounting holes; 4 leads		
SOT313-2	LQFP48	plastic low profile quad flat package; 48 leads; body 7 x 7 x 1.4 mm	MS-026 (JEDEC) 136E05 (IEC)	

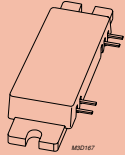
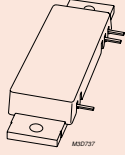
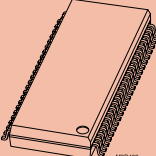
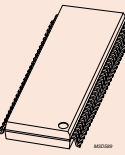
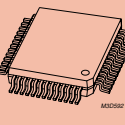
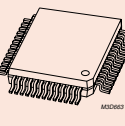

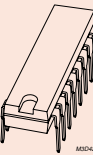
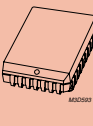
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT314-2	LQFP64	plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm	MS-026 (JEDEC) 136E10 (IEC)	
SOT315-1	LQFP80	plastic low profile quad flat package; 80 leads; body 12 x 12 x 1.4 mm	MS-026 (JEDEC) 136E15 (IEC)	
SOT323	UMT3; CMPAK	Plastic surface mounted package; 3 leads; body 2.0 x 1.25 x 0.95 mm	SC-70 (EIAJ)	
SOT337-1	SSOP14	plastic shrink small outline package; 14 leads; body width 5.3 mm	MO-150 (JEDEC)	
SOT338-1	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	MO-150 (JEDEC)	
SOT339-1	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	MO-150 (JEDEC)	
SOT340-1	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	MO-150 (JEDEC)	
SOT341-1	SSOP28	plastic shrink small outline package; 28 leads; body width 5.3 mm	MO-150 (JEDEC)	
SOT343R	CMPAK-4	Plastic surface mounted package; reverse pinning; 4 leads		

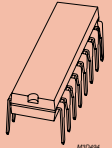
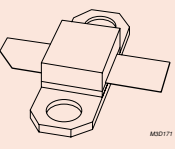
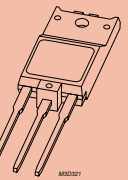
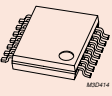
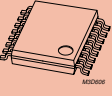
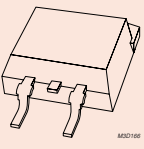
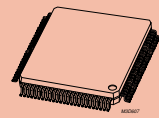
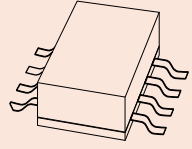
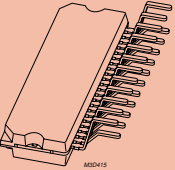
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT346	SMT3; MPAK	Plastic surface mounted package; 3 leads; body 2.9 x 1.5 x 1.5 mm	SC-59A (EIAJ) TO-236 (JEDEC)	
SOT353	UMT5	Plastic surface mounted package; 5 leads; body 2.0 x 1.25 x 0.95 mm	SC-88A (EIAJ)	
SOT355-1	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	MO-153 (JEDEC)	
SOT358-1	LQFP32	plastic low profile quad flat package; 32 leads; body 7 x 7 x 1.4 mm	MS-026 (JEDEC) 136E03 (IEC)	
SOT360-1	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	MO-153 (JEDEC)	
SOT361-1	TSSOP28	plastic thin shrink small outline package; 28 leads; body 9.7 x 4.4 x 0.875 mm	MO-153 (JEDEC)	
SOT362-1	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	MO-153 (JEDEC)	
SOT363	UMT6	Plastic surface mounted package; 6 leads; body 2.0 x 1.25 x 0.95 mm	SC-88; SC-70-6 (EIAJ)	
SOT364-1	TSSOP56	plastic thin shrink small outline package; 56 leads; body width 6.1 mm	MO-153 (JEDEC)	

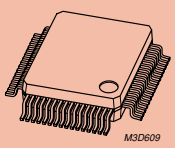
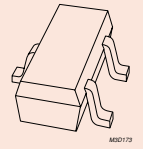
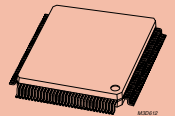
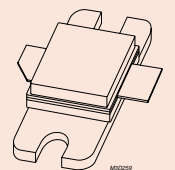
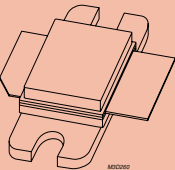
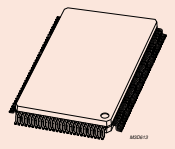
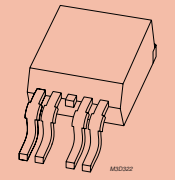
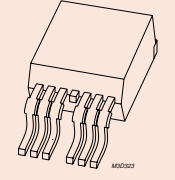
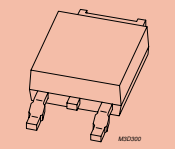
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT365A		Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 4 in-line leads		
SOT365C		Plastic rectangular single-ended flat package; flange mounted; 2 mounting holes; 3 in-line leads		
SOT370-1	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	MO-118 (JEDEC)	
SOT371-1	SSOP56	plastic shrink small outline package; 56 leads; body width 7.5 mm	MO-118 (JEDEC)	
SOT379-1	QFP52	plastic quad flat package; 52 leads (lead length 1.6 mm); body 10 x 10 x 2.0 mm	MS-022 (JEDEC) 135E04 (IEC)	
SOT379-2	QFP52	plastic quad flat package; 52 leads (lead length 1.6 mm); body 10 x 10 x 2.0 mm	MS-022 (JEDEC)	
SOT380-1	PLCC20	plastic leaded chip carrier; 20 leads	EDR-7319 (EIAJ) MS-018 (JEDEC) 112E04 (IEC)	
SOT38-1	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SC-503-16 (EIAJ) MO-001 (JEDEC) 050G09 (IEC)	
SOT381-1	logic package	32 plastic leaded chip carrier		

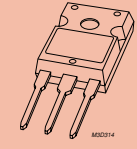
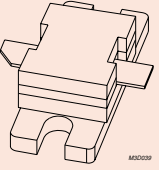
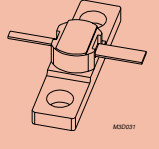
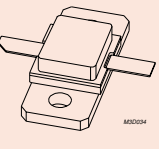
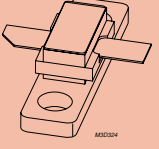
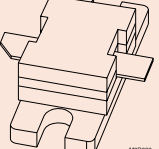
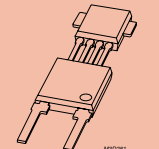
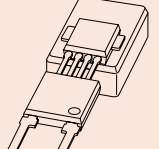
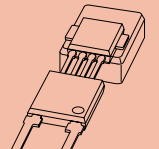
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT38-4	DIP16	plastic dual in-line package; 16 leads (300 mil)		
SOT390A		Flanged ceramic package; 2 mounting holes; 2 leads		
SOT399	TOP-3D	Plastic single-ended through-hole package; mountable to heatsink; 1 mounting hole; 3 in-line leads		
SOT402-1	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	MO-153 (JEDEC)	
SOT403-1	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	MO-153 (JEDEC)	
SOT404	D ² -PAK	Plastic single-ended surface mounted package (Philips version of D ² -PAK); 3 leads (one lead cropped); body 9.4 x 10.0 x 4.3 mm		
SOT407-1	LQFP100	plastic low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm	MS-026 (JEDEC) 136E20 (IEC)	
SOT409A		Ceramic surface mounted package; 8 leads		
SOT411	DBS23P	Plastic DIL-bent-SIL power package; 23 leads (straight lead length 3.2 mm)		

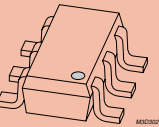
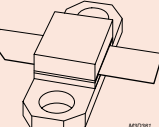
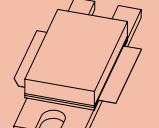
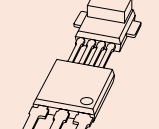
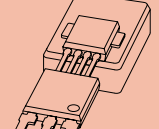
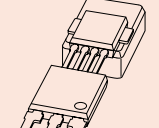
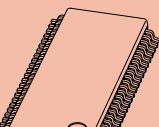
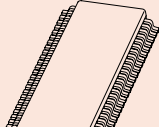
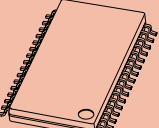
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT414-1	LQFP64	plastic low profile quad flat package; 64 leads; body 7 x 7 x 1.4 mm	MS-026 (JEDEC) 136E06 (IEC)	
SOT416	EMT3; SMPAK	Plastic surface mounted package; 3 leads; body 1.6 x 0.8 x 0.77 mm	SC-75 (EIAJ)	
SOT420-1	LQFP128	plastic low profile quad flat package; 128 leads; body 14 x 14 x 1.4 mm	MS-026 (JEDEC)	
SOT422A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT423A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT425-1	LQFP128	plastic low profile quad flat package; 128 leads; body 14 x 20 x 1.4 mm	MS-026 (JEDEC) 136E28 (IEC)	
SOT426	D ² -PAK	Plastic single-ended surface mounted package (Philips version of D ² -PAK); 5 leads (one lead cropped)		
SOT427	D ² -PAK	Plastic single-ended surface mounted package (Philips version of D ² -PAK); 7 leads (one lead cropped)		
SOT428	SC-63; D-PAK	Plastic single-ended surface mounted package (Philips version of D-PAK); 3 leads (one lead cropped); body 6.1 x 6.6 x 2.3 mm	SC-63 (EIAJ) TO-252 (JEDEC)	

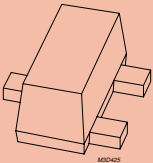
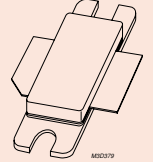
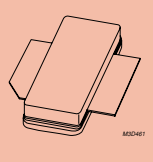
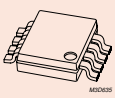
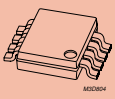
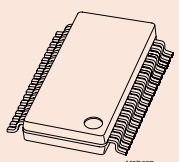
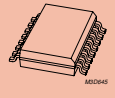
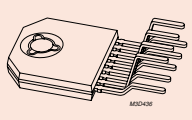
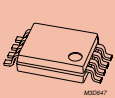
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT429	TO-247	Flanged hermetic ceramic package; 2 mounting holes; 2 leads Plastic single-ended through-hole package; heatsink mounted; 1 mounting hole; 3 lead TO-247	TO-247 (JEDEC)	
SOT439A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT440A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT443A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT445C		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT448A		Flanged hermetic ceramic package; 2 mounting holes; 2 leads		
SOT453A		Plastic single-ended multi-chip package; magnetized ferrite magnet (3.8 x 2 x 0.8 mm); 4 interconnections; 2 in-line leads		
SOT453B		Plastic single-ended multi-chip package; magnetized ferrite magnet (8 x 8 x 4.5 mm); 4 interconnections; 2 in-line leads		
SOT453C		Plastic single-ended multi-chip package; magnetized ferrite magnet (5.5 x 5.5 x 3 mm); 4 interconnections; 2 in-line leads		

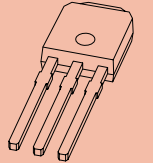
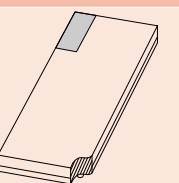
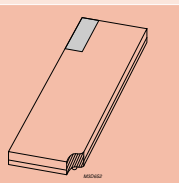
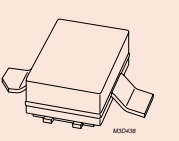
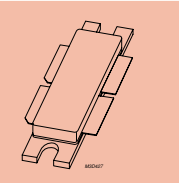
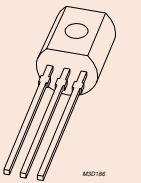
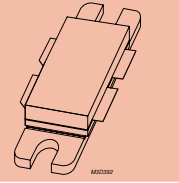
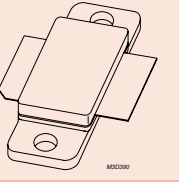
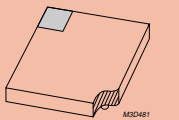
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Package version	Package name	Package description	Industry tyoes	3D Line drawing
SOT457	TSOP6; SMT6; SSOT6	Plastic surface mounted package; 6 leads; body 2.9 x 1.5 x 0.95 mm	SC-74 (EIAJ)	
SOT467C	LDMOST	Flanged LDMOST ceramic package; 2 mounting holes; 2 leads; Package under development		
SOT468A		Flanged ceramic (AlN) package; 2 mounting holes; 2 leads		
SOT477A		Plastic single-ended multi-chip package; magnetized ferrite magnet (3.8 x 2 x 0.8 mm); 4 interconnections; 3 in-line leads		
SOT477B		Plastic single-ended multi-chip package; magnetized ferrite magnet (8 x 8 x 4.5 mm); 4 interconnections; 3 in-line leads		
SOT477C		Plastic single-ended multi-chip package; magnetized ferrite magnet (5.5 x 5.5 x 3 mm); 4 interconnections; 3 in-line leads		
SOT480-1	TSSOP48	plastic thin shrink small outline package; 48 leads; body 9.7 x 4.4 x 0.9; lead pitch 0.4 mm	MO-153 (JEDEC)	
SOT481-2	TSSOP56	plastic thin shrink small outline package; 56 leads; body width 4.4 mm	MO-194 (JEDEC)	
SOT487-1	TSSOP32	plastic thin shrink small outline package; 32 leads; body width 6.1 mm; lead pitch 0.65 mm	MO-153 (JEDEC)	

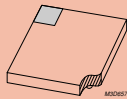
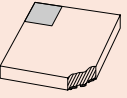
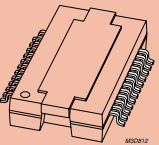

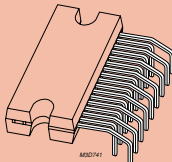
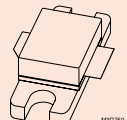
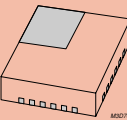
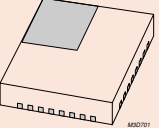
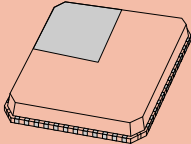
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT490	SC-89	Plastic surface mounted package; 3 flatleads; body 1.6 x 0.85 x 0.7 mm	SC-89 (EIAJ)	
SOT502A	LDMOST	Flanged LDMOST ceramic package; 2 mounting holes; 2 leads		
SOT502B	LDMOST	Earless flanged LDMOST ceramic package; 2 leads		
SOT505-1	TSSOP8	plastic thin shrink small outline package; 8 leads; body 3.0 x 3.0 x 0.875 mm		
SOT505-2	TSSOP8	plastic thin shrink small outline package; 8 leads; body 3.0 x 4.0 x 0.85 mm; lead length 0.5 mm		
SOT510-1	TSSOP38	plastic thin shrink small outline package; 38 leads; body 9.7 x 4.4 x 0.9 mm; lead pitch 0.5 mm		
SOT519-1	SSOP16	plastic shrink small outline package; 16 leads; body 4.9 x 3.9 x 1.475 mm; lead pitch		
SOT523-1	LC9P; DBS9P	Plastic DIL-bent-SIL power package; 9 leads (lead length 12/11 mm); exposed die pad. Dimensions H x W = 14.7 x 13.2 mm		
SOT530-1	TSSOP8	plastic thin shrink small outline package; 8 leads; body 3.0 x 4.4 x 0.9 mm	MO-153 (JEDEC)	

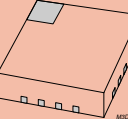
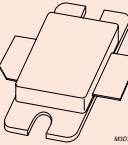
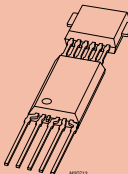
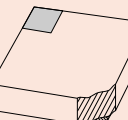
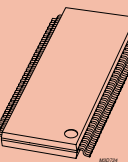
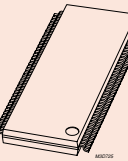
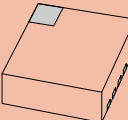
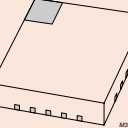
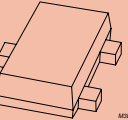
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT533	I-PAK	Plastic single-ended package (Philips version of I-PAK); 3 leads (in-line)		
SOT536-1	LFBGA96	plastic low profile fine-pitch ball grid array package; 96 balls; body 13.5 x 5.5 x 1.05 mm		
SOT537-1	LFBGA114	plastic low profile fine-pitch ball grid array package; 114 balls; body 16 x 5.5 x 1.05 mm		
SOT538A		Ceramic surface mounted package; 2 leads		
SOT539A	LDMOST	Flanged balanced LDMOST ceramic package; 2 mounting holes; 4 leads		
SOT54	SPT; E-1	Plastic single-ended leaded (through hole) package; 3 leads; body 5.1 x 4.6 x 3.9 mm	SC-43A (EIAJ) TO-92 (JEDEC)	
SOT540A	LDMOST	Flanged balanced LDMOST ceramic package; 2 mounting holes; 4 leads		
SOT541A	LDMOST	Flanged LDMOST ceramic package; 2 mounting holes; 2 leads		
SOT543-1	TFBGA64	plastic thin fine-pitch ball grid array package; 64 balls; body 6 x 6 x 0.8 mm	MO-195 (JEDEC)	

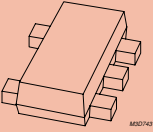
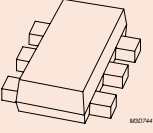
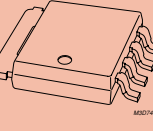
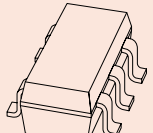
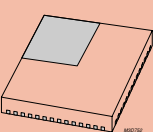
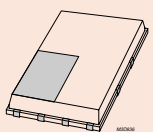
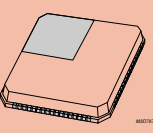
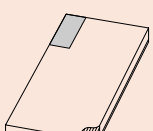
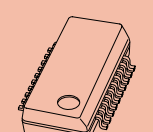
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT556-1	SSOP24	plastic shrink small outline package; 24 leads; body width 3.9 mm; lead pitch 0.635 mm	MO-137 (JEDEC)	
SOT560	HBCC32	plastic thermal enhanced bottom chip carrier; 32 terminals; body 5 x 5 x 0.65 mm		
SOT566-3	HSOP24	Plastic thermal enhanced small outline package; 24 leads; low stand-off height; heatsink. Dimensions H x W = 2.9 x 13.0 mm		
SOT569-1	TFBGA144	Plastic thin fine-pitch ball grid array package; 144 balls; body 12 x 12 x 0.8 mm	MO-216 (JEDEC)	
SOT577-2	SIL17 ST bending; RDBS17P	Plastic rectangular-DIL-bent-SIL power package; 17 leads (row spacing 2.54 mm). Dimensions H x W = 12.2 x 20.0 mm		
SOT608A		Flanged ceramic package; 2 mounting holes; 2 leads; Package under development		
SOT616-1	HVQFN24	plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm	MO-220 (JEDEC)	
SOT617-1	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm	MO-220 (JEDEC)	
SOT619-2	HVQFN48	plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm	MO-220 (JEDEC)	

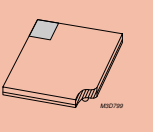
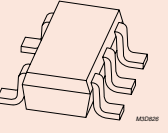
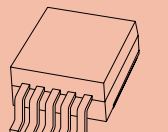
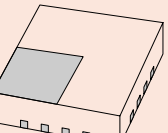
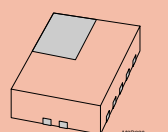
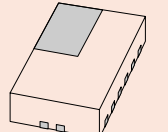
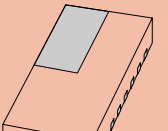
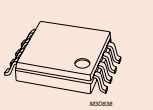
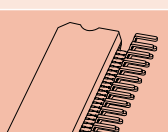
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT629-1	HVQFN16	plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 x 4 x 0.85 mm	MO-220 (JEDEC)	
SOT634A		Flanged ceramic package; 2 mounting holes; 2 leads; Package under development		
SOT637		Plastic single-ended multi-chip package; 6 interconnections; 5 in-line leads		
SOT639-2	HBCC16	plastic thermal enhanced bottom chip carrier; 16 terminals; body 3 x 3 x 0.65 mm	MO-217 (JEDEC)	
SOT646-1	TSSOP64	plastic thin shrink small outline package; 64 leads; body width 6.1 mm	MO-153 (JEDEC)	
SOT647-1	TSSOP80	plastic thin shrink small outline package; 80 leads; body width 6.1 mm	MO-153 (JEDEC)	
SOT650-1	HVSON10	Plastic thermal enhanced very thin small outline package; no leads; 10 terminals; body 3 x 3 x 0.85 mm	MO-229 (JEDEC)	
SOT662-1	HVQFN20	plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 5 x 5 x 0.85 mm	MO-220 (JEDEC)	
SOT663		Plastic surface mounted package; 3 flatleads; body 1.6 x 1.2 x 0.55 mm		

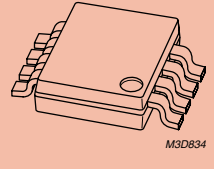
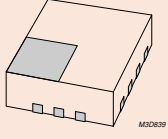
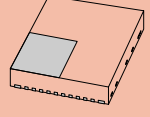
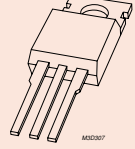
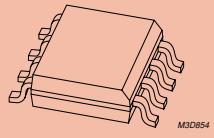
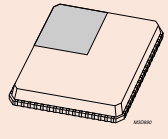
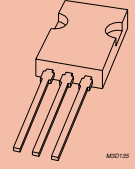
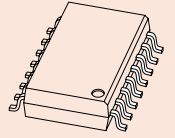
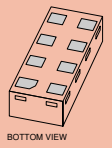
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT665	SO5	Plastic surface mounted package; 5 flatleads; body 1.6 x 1.2 x 0.55 mm		
SOT666	HVQFN56	Plastic surface mounted package; 6 flatleads; body 1.6 x 1.2 x 0.55 mm		
SOT669	LFPK	Plastic single-ended surface mounted package (Philips version of LFPK); 4 leads; body 3.95 x 4.9 x 1.02 mm		
SOT680-1	SO5	plastic small outline package; 5 leads; body 2.9 x 1.6 x 1.1 mm	MO-178 (JEDEC)	
SOT684-1	HVQFN56	plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm	MO-220 (JEDEC)	
SOT685-1	HVSON8; QLPAK	plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 6 x 5 x 0.85 mm		
SOT687	HVQFN68	plastic, heatsink very thin quad flat package; no leads; 68 terminals; body 10 x 10 x 0.85 mm		
SOT702-1	VFBGA56	plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm	MO-225 (JEDEC)	
SOT724-1	SSOP20	plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm	MO-137 (JEDEC)	

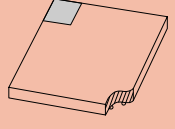
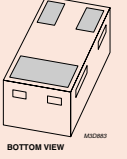
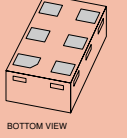
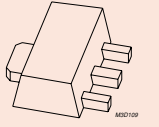
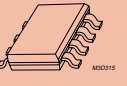
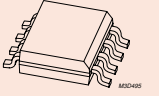
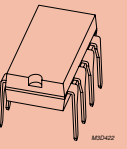
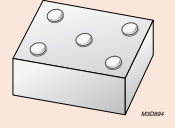
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Package version	Package name	Package description	Industry types	3D Line drawing
SOT746-1	TFBGA64	plastic thin fine-pitch ball grid array package; 64 balls; body 7 x 7 x 0.7 mm	MO-195 (JEDEC)	
SOT753		Plastic surface mounted package; 5 leads; body 2.9 x 1.5 x 0.95 mm	SC-74A (EIAJ)	
SOT756	SPAK-5	Plastic single-ended surface mounted package; 5 leads, body 9.015 x 9.39 x 1.905 mm		
SOT758-1	HVQFN16	plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm	MO-220 (JEDEC)	
SOT762-1	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm		
SOT763-1	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm		
SOT764-1	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm		
SOT765-1	VSSOP8	plastic very thin shrink small outline package; 8 leads; body 2.0 x 2.3 x 0.725 mm	MO-187 (JEDEC)	
SOT767-1	SIL23P; DBS27P	Plastic DIL-bent-SIL (special bent) power package; 27 leads (lead length 7.7 mm). Dimensions H x W = 12.2 x 28.0 mm		

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Package version	Package name	Package description	Industry types	3D Line drawing
SOT770-1	HTSSOP8	plastic thermal enhanced thin shrink small outline package; 8 leads; body 3.0 x 3.0 x 0.85 mm; exposed die pad		
SOT773-1	HVQFN14	plastic thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 2.5 x 0.85 mm		
SOT776	HSSON14	Plastic thermal enhanced shrink small outline package; no leads; 14 terminals; body 12 x 12 x 2.1 mm		
SOT78	TO-220AB; SC-46	Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB; body 15.5 x 10.0 x 4.3 mm	SC-46 (EIA) 3-lead TO-220AB (JEDEC)	
SOT786-2	HSO8	Plastic thermal enhanced small outline package; 8 leads; body width 3.9 mm; exposed die pad		
SOT804-1	HVQFN64	plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm	MO-220 (JEDEC)	
SOT82		Plastic single-ended package; 3 leads (in-line)		
SOT820	HSO16	Plastic thermal enhanced small outline package; 16 leads; body width 7.5 mm; heatsink		
SOT833-1	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm	MO-252 (JEDEC)	

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Package version	Package name	Package description	Industry types	3D Line drawing
SOT857-1	TFBGA128	plastic thin fine-pitch ball grid array package; 128 balls; body 9 x 9 x 0.8 mm	MO-195 (JEDEC)	
SOT883	SC-101	Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm	SC-101 (EIA)	
SOT886	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm	MO-252 (JEDEC)	
SOT89	MPT3; UPAK	Plastic surface mounted package; collector pad for good heat transfer; 3 flatleads; body 4.5 x 2.5 x 1.5 mm	SC-62 (EIA) TO-243 (JEDEC)	
SOT96	SO8	Plastic small outline package; 8 leads; body width 3.9 mm	MS-012AA (JEDEC) 076E03S (IEC)	
SOT96-1	SO8	plastic small outline package; 8 leads; body 4.9 x 3.9 x 1.35 mm	MS-012 (JEDEC) 076E03 (IEC)	
SOT97-1	DIP8	plastic dual in-line package; 8 leads (300 mil)	SC-504-8 (EIA) MO-001 (JEDEC) 050G01 (IEC)	
WLCSP	DIP8	body; 0.87 x 1.30 x 0.447	CSP	

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